

4

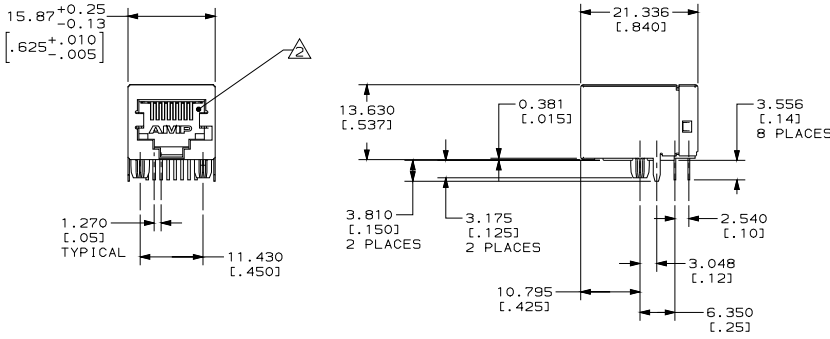
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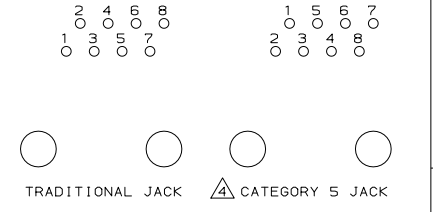
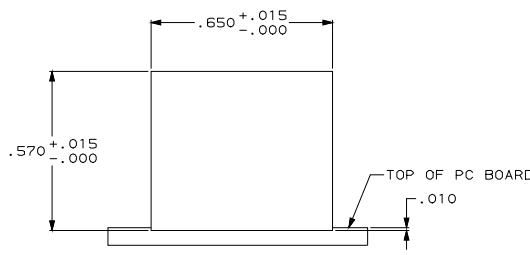
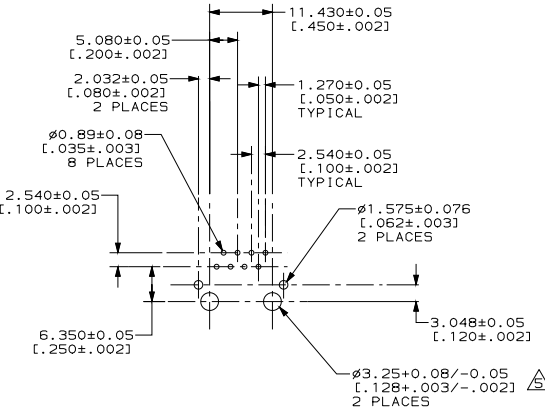
1

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LOC	DIST	REVISIONS			
AA	22	REV	DESCRIPTION	DATE	BY
E		REVISED PER EC	OS11-0140-03	26AUG03	DLD/BDK

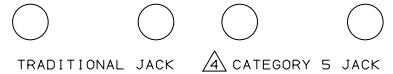


- △ MATERIAL: HOUSING HIGH TEMPERATURE NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0. TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [0.00150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE. SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 2.03µm[.00080] MINIMUM TIN-LEAD OVER 2.54µm[.00100] MINIMUM COPPER.
- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
- △ CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF TRADITIONAL JACKS.
- △ USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.



SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE

SUGGESTED PANEL CUTOUT
SCALE 4:1



558342-1
PART NUMBER

<small>THE DIMENSIONS ON THIS DRAWING ARE NOMINAL UNLESS OTHERWISE SPECIFIED. DIMENSIONS SHALL BE REPORTED FOR THE LARGEST SIZE.</small>		DIM: T. PLITS 2-2-94 CHK: S. FOX 2-16-94 APPD: S. FOX 2-16-94	AMP AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	DIMENSIONS SPECIFIED: Ø PLC ±.010 Ø PLC ±.015 Ø PLC ±.020 H. PLC ±.010 ANGLES ±.010	DES. RECD: 108-1163 PRODUCT SPEC: 108-1163 APPLICATION SPEC: 114-2048 WEIGHT: -	MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, LOW PROFILE, SHIELDED, PC BOARD GROUND, CATEGORY 5
MATERIAL: △ FINISH: △	SIZE: A2 CASE CODE: 00779 DRAWING NO: C-558342	CUSTOMER DRAWING	SCALE: 2:1 SHEET 1 OF 1 REV E

558342

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